



40V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(on) Max	ID MAX Ta = +25°C
40\/	11mΩ @ V _{GS} = -10V	-10A
-40V	19mΩ @ V _{GS} = -4.5V	-8A

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-Resistance
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- DC-DC converters
- · Power-management functions
- Analog switches

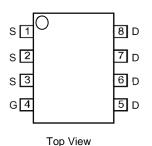
Mechanical Data

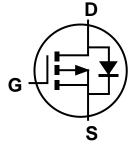
- Package: SO-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Leadframe.
 Solderable per MIL-STD-202, Method 208 (3)

 Output

 Description:
- Weight: 0.074 grams (Approximate)







Equivalent Circuit

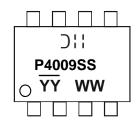
Ordering Information (Note 4)

Part Number	Daelrage	Packing		
Part Number	Package	Qty.	Carrier	
DMP4009SSS-13	SO-8	2,500	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



);; = Manufacturer's Marking
P4009SS= Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 23 = 2023)
WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	-40	V		
Gate-Source Voltage	V_{GSS}	±20	V		
Continuous Drain Current (Note 6) V _{GS} = -10V	lo	-10 -7	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	-104	Α	
Maximum Body Diode Continuous Current (Note 6)	Is	-10	Α		
Pulsed Source Current (10µs Pulse, Duty Cycle = 1%)			lsм	-104	Α
Avalanche Current, L = 1mH	las	-25.7	Α		
Avalanche Energy, L = 1mH	Eas	330	mJ		

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	Reja	79	°C/W
Total Power Dissipation (Note 6)	PD	2.1	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	58.5	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

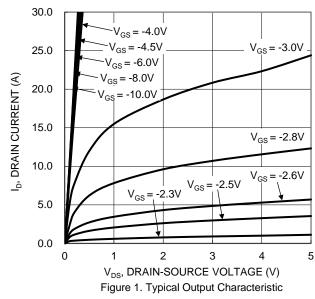
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-40		_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	-1	μA	V _{DS} = -40V, V _{GS} = 0V	
Gate-Source Leakage	IGSS	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(th)	-1.0	_	-2.5	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
Static Drain-Source On-Resistance	Pro/orn	_	7	11	mΩ	$V_{GS} = -10V, I_D = -9.8A$	
Static Diain-Source On-Nesistance	RDS(ON)	_	9.5	19	11152	$V_{GS} = -4.5V, I_{D} = -9.8A$	
Diode Forward Voltage	VsD	_	-0.7	-1	V	$V_{GS} = 0V$, $I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	5697	_		V _{DS} = -20V, V _{GS} = 0V f = 1MHz	
Output Capacitance	Coss	_	534	_	pF		
Reverse Transfer Capacitance	Crss	_	408	_			
Gate Resistance	R_g	_	7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (VGS = -4.5V)	Q_g	_	53	_			
Total Gate Charge (V _{GS} = -10V)	Q_g	_	112	_	nC	$V_{DS} = -20V, I_{D} = -9.8A$	
Gate-Source Charge	Qgs	_	20	_	110		
Gate-Drain Charge	Q_{gd}	_	18	_			
Turn-On Delay Time	t _{D(ON)}	_	11.5	_		V _{GS} = -10V, V _{DD} = -20V,	
Turn-On Rise Time	t _R	_	41	_	no		
Turn-Off Delay Time	tD(OFF)	_	146	_	ns	$R_G = 2\Omega$, $I_D = -9.8A$	
Turn-Off Fall Time	tF	_	165	_			
Reverse Recovery Time	trr	_	27	_	ns	$I_F = -9.8A$, $di/dt = -100A/\mu s$	
Reverse Recovery Charge	Q_{RR}	_	22	_	nC	$I_F = -9.8A$, $di/dt = -100A/\mu s$	

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.





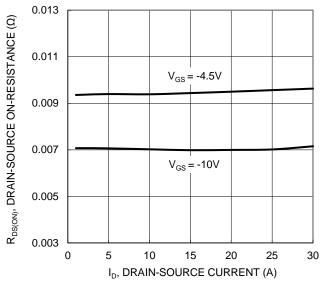


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

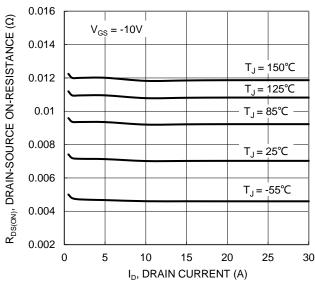
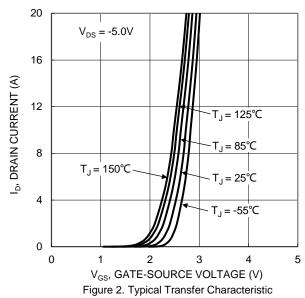
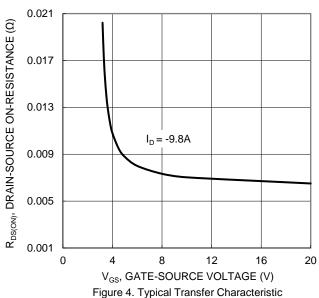


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





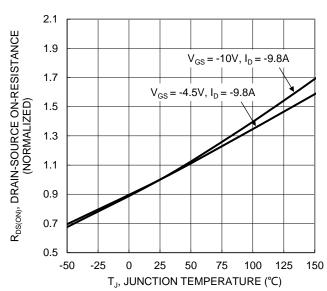


Figure 6. On-Resistance Variation with Junction Temperature



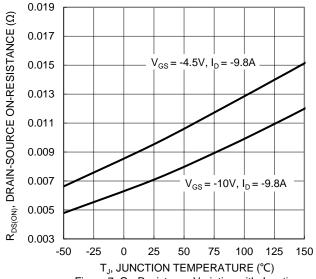


Figure 7. On-Resistance Variation with Junction Temperature

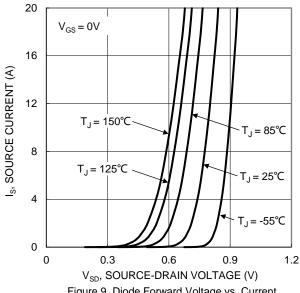


Figure 9. Diode Forward Voltage vs. Current

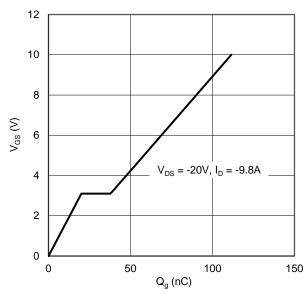


Figure 11. Gate Charge

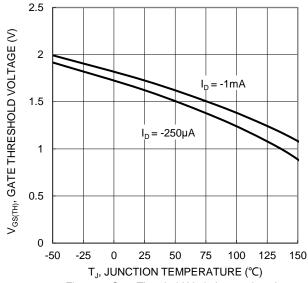
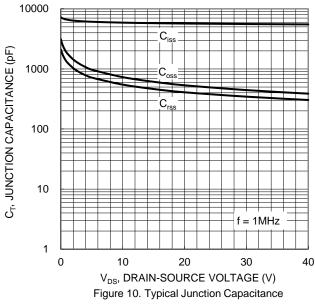


Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 R_{DS(ON)} $P_{W} = 100 \mu s$ 100 ID, DRAIN CURRENT (A) 10 $T_{J(Max)} = 150$ °C $P_{W} = 100 ms$ $T_A = 25^{\circ}C$ Single Pulse 0.1 DUT on 1*MRP Board $V_{GS} = -10V$ 0.01 0.01 10 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area



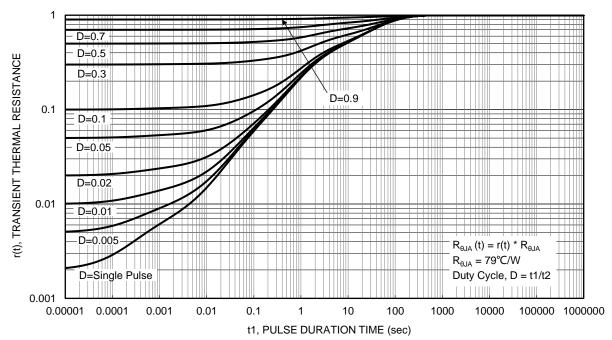
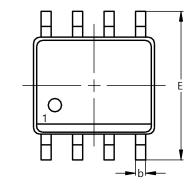


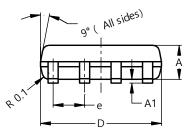
Figure 13. Transient Thermal Resistance

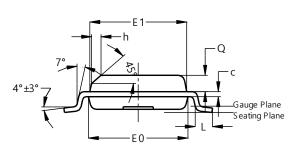


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.







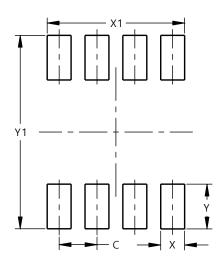
SO-8

SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
С	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
е			1.27			
h			0.35			
L	0.62	0.82	0.72			
Ø	0.60	0.70	0.65			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dimensions	Value (in mm)
С	1.27
X	0.802
X1	4.612
Υ	1.505
V1	6.50



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